

L Number	Hits	Search Text	DB	Time stamp
47	9	(257/737 or 257/786) and (aluminum or "Al") with (pad or electrode) and barrier with ("Ni" or nickel) and (copper or "Cu") near (layers or films) and solder with eutectic	USPAT	2004/05/26 19:43
48	16	(257/737 or 257/786) and (aluminum or "Al") with (pad or electrode) and barrier with ("Ni" or nickel) and (copper or "Cu") and solder with eutectic	USPAT	2004/05/26 19:17
49	8	(257/737 or 257/786) and (aluminum or "Al") with (pad or electrode) and barrier with ("Ni" or nickel) with (copper or "Cu") and solder with eutectic	USPAT	2004/05/26 19:18
50	3	(257/737 or 257/786) and (aluminum or "Al") with (pad or electrode) and (barrier or IBM) with ("Ni" or nickel) and (upper near barrier or UBM) with (copper or "Cu") and solder with eutectic	USPAT	2004/05/26 19:19
51	7	(aluminum or "Al") with (wir\$3 or metal or circuit) and (copper or "Cu") with (pad or electrode) and (barrier or IBM) with ("Ni" or nickel) and (upper near barrier or UBM) with (copper or "Cu") and solder with eutectic	USPAT	2004/05/26 19:23
52	8	(aluminum or "Al") with (wir\$3 or metal or circuit) and (copper or "Cu") with (pad or electrode) and (barrier or LBM) with ("Ni" or nickel) and (under-bump near metallurgy or UBM) with (copper or "Cu") and solder with eutectic	USPAT	2004/05/26 19:23
53	3153	257/737	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/26 20:53
54	226	257/737 and barrier with pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/26 19:46
55	2440	257/737 and pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/26 19:46
56	1898	257/737 and pad and wir\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/26 20:38
57	0	(257/737 and pad and wir\$3) not (257/737 and pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/26 20:38
58	542	(257/737 and pad) not (257/737 and pad and wir\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/26 20:39
59	1255	257/737 not (257/737 and pad and wir\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/26 20:39
60	2623	257/738	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/26 21:14

61	2150	257/738 and pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/26 21:05
62	1234	257/738 and pad with wir\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/26 20:56
63	14	5705428.pn. or 5937320.pn. or 6127731.pn. or 6140703.pn. or 6293457.pn. or 6306751.pn. or 6373137.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/26 21:01
64	7	5705428.pn. or 5937320.pn. or 6127731.pn. or 6140703.pn. or 6293457.pn. or 6306751.pn. or 6373137.pn.	USPAT	2004/05/26 21:01
65	916	(257/738 and pad) not (257/738 and pad with wir\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/26 21:05
66	281	257/739	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/26 22:15
67	2501	257/786	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/26 21:17
68	2000	257/786 and pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/26 22:06
69	501	257/786 not (257/786 and pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/26 22:09
70	17	(semiconductor or die or chip or IC) with (trench or recess or groove) with top near surface and (pad or electrode or contact) with slits	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/26 22:14
71	196	(semiconductor or die or chip or IC) and (trench or recess or groove) with upper near surface and (pad or electrode or contact) with slits	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/26 22:20
72	1919	257/750	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/26 22:39
73	231	(semiconductor or die or chip or IC) and (trench or recess or groove) with align\$4 and (pad or electrode or contact) with slits	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/26 22:31
80	1645	(semiconductor or die or chip or IC) and (trench or recess or groove) with align\$4 and (pad or electrode or contact) with (channels)	USPAT	2004/05/26 22:33

81	1103	(semiconductor or die or chip or IC) and (trench or recess or groove) with align\$4	USPAT	2004/05/26 22:34
82	2445	and (pad or contact) with (channels) 257/751	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/26 22:39
83	393	257/751 and pad and barrier	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/26 22:40
84	51	257/751 and pad and metallurgy	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/26 22:41
85	124	(257/762 or 257/763 or 257/766) and pad and metallurgy	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/26 22:44
86	212	(257/772 or 257/773 or 257/779) and pad and metallurgy	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/26 22:49
87	218	(257/784 or 257/780 or 257/781) and pad and metallurgy	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/26 22:52
88	144	(257/786 or 228/254) and pad and metallurgy	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/26 22:52